| [TuF2] Processing for 3D Integration | |
|---|---|
| **Session Date** | November 11 (Tue.), 2025 |
| **Session Time** | 14:50-16:25 |
| **Session Room** | Room F (Panorama Room, 16F) |
| **Session Chair** | Dr. Kwang-Seong Choi (ETRI, Korea) |

**[TuF2-1] [Plenary]** **14:50-15:35**

**Advanced Packaging Technology with Cu-Cu Hybrid Bonding**

Takafumi (Tak) Fukushima (Tohoku Univ., Japan)

**[TuF2-2] [Invited]** **15:35-16:05**

**Vertical Fan-Out (VFO) Technology for Memory and Storage Applications**

Ji Yong Park (SK hynix Inc., Korea)

**[TuF2-3] [Invited]** **16:05-16:25**

**Enabling 3D Integration: Advances in Hybrid Wafer Bonding Technology**

Thomas Kasbauer (EV Group, Austria)